



# SOD323F

plastic surface-mounted package; 2 leads

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	SOD323F
<b>Package type industry code</b>	SOD323F
<b>Package style descriptive code</b>	SOD (small outline diode)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEITA package outline code</b>	SC-90
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	16-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.6	-	1.7	1.8	mm
E	package width	1.15	-	1.25	1.35	mm
A	seated height	0.65	-	0.7	0.8	mm
n <sub>2</sub>	actual quantity of termination	-	-	2	-	



## 2. Package outline

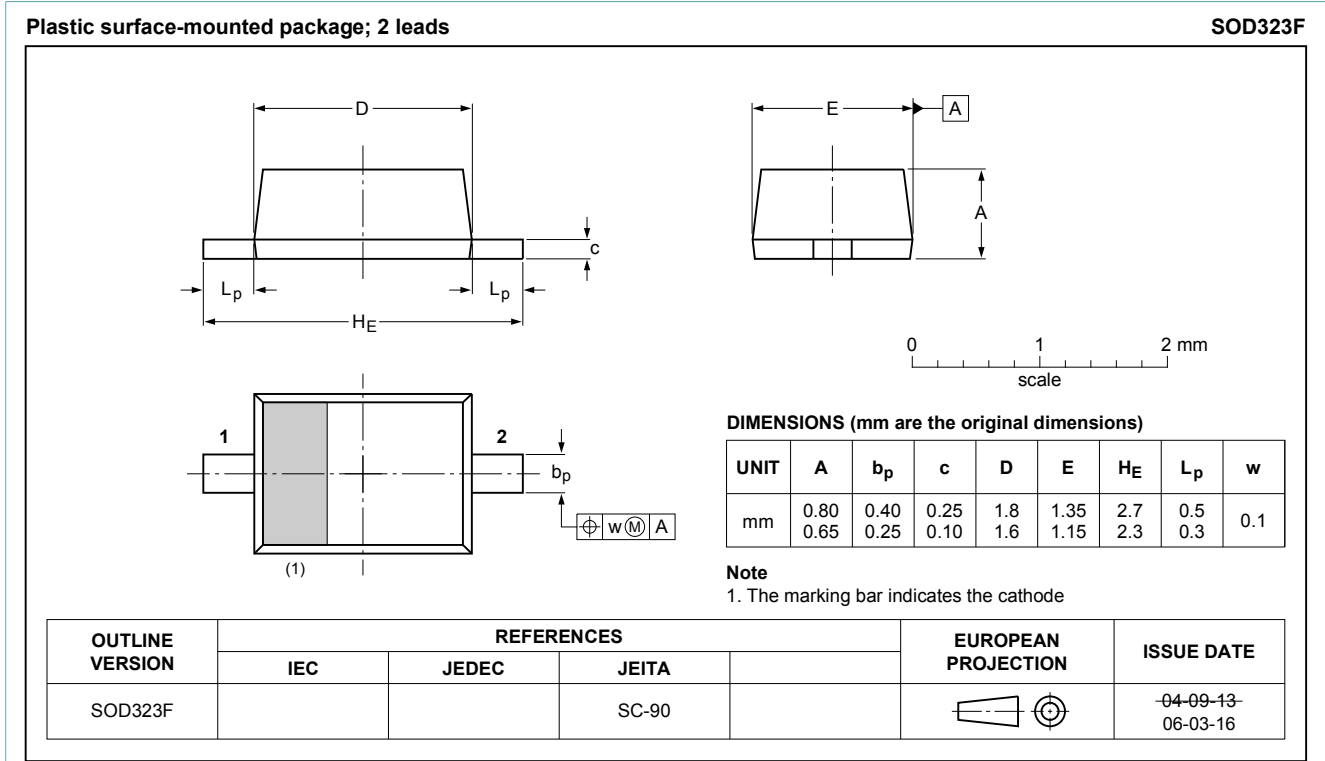


Fig. 1. Package outline SOD323F

## 3. Soldering

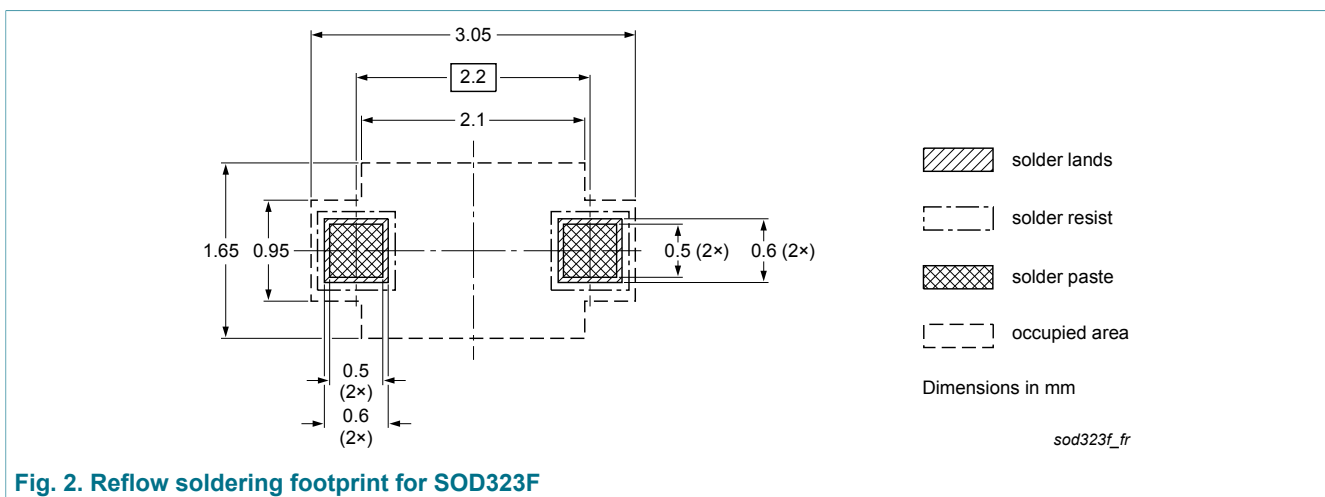


Fig. 2. Reflow soldering footprint for SOD323F

## 4. Legal information

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